

#### Is Now Part of



## ON Semiconductor®

## To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (\_), the underscore (\_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (\_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at <a href="www.onsemi.com">www.onsemi.com</a>. Please email any questions regarding the system integration to Fairchild <a href="guestions@onsemi.com">guestions@onsemi.com</a>.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer





# H11AA1M, H11AA4M 6-Pin DIP AC Input Phototransistor Optocouplers

#### **Features**

- Bi-polar Emitter Input
- Built-in Reverse Polarity Input Protection
- Safety and Regulatory Approvals:
  - UL1577, 4,170 VAC<sub>RMS</sub> for 1 Minute
  - DIN-EN/IEC60747-5-5, 850 V Peak Working Insulation Voltage

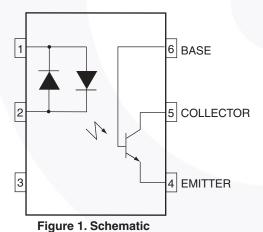
## **Applications**

- AC Line Monitor
- Unknown Polarity DC Sensor
- Telephone Line Interface

#### **Description**

The H11AA1M and H11AA4M devices consist of two gallium-arsenide infrared emitting diodes connected in inverse parallel driving a single silicon phototransistor output.

#### **Schematic**



## **Package Outlines**

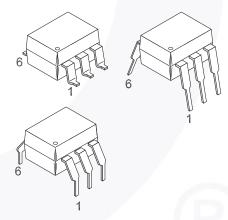


Figure 2. Package Outlines

## **Safety and Insulation Ratings**

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter		Characteristics
Installation Classifications per DIN VDE	< 150 V <sub>RMS</sub>	I–IV
0110/1.89 Table 1, For Rated Mains Voltage	< 300 V <sub>RMS</sub>	I–IV
Climatic Classification		55/100/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
\/	Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$ , Type and Sample Test with $t_m = 10$ s, Partial Discharge < 5 pC	1360	V <sub>peak</sub>
V <sub>PR</sub>	Input-to-Output Test Voltage, Method B, V <sub>IORM</sub> x 1.875 = V <sub>PR</sub> , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC	1594	V <sub>peak</sub>
V <sub>IORM</sub>	Maximum Working Insulation Voltage	850	V <sub>peak</sub>
V <sub>IOTM</sub>	Highest Allowable Over-Voltage	6000	V <sub>peak</sub>
	External Creepage	≥ 7	mm
	External Clearance	≥ 7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
T <sub>S</sub>	Case Temperature <sup>(1)</sup>	175	°C
I <sub>S,INPUT</sub>	Input Current <sup>(1)</sup>	350	mA
P <sub>S,OUTPUT</sub>	Output Power <sup>(1)</sup>	800	mW
R <sub>IO</sub>	Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V <sup>(1)</sup>	> 10 <sup>9</sup>	Ω

#### Note:

1. Safety limit values – maximum values allowed in the event of a failure.

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Unit
TOTAL DEVIC	CE		
T <sub>STG</sub>	Storage Temperature	-40 to +125	°C
T <sub>OPR</sub>	Operating Temperature	-40 to +100	°C
T <sub>J</sub>	Junction Temperature	-40 to +125	°C
T <sub>SOL</sub>	Lead Solder Temperature	260 for 10 seconds	°C
Total Device Power Dissipation @ 25°C 270		270	mW
$P_{D}$	Derate Linearly From 25°C	2.94	mW/°C
EMITTER			
I <sub>F</sub>	Continuous Forward Current	60	mA
I <sub>F</sub> (pk)	Forward Current - Peak (1 µs pulse, 300 pps)	±1.0	А
В	LED Power Dissipation @ 25°C	120	mW
$P_{D}$	Derate Linearly From 25°C	1.41	mW/°C
DETECTOR			
I <sub>C</sub>	Continuous Collector Current	50	mA
P <sub>D</sub>	Detector Power Dissipation @ 25°C	150	mW
	Derate linearity from 25°C	1.76	mW/°C

#### **Electrical Characteristics**

 $T_A = 25^{\circ}C$  Unless otherwise specified.

## **Individual Component Characteristics**

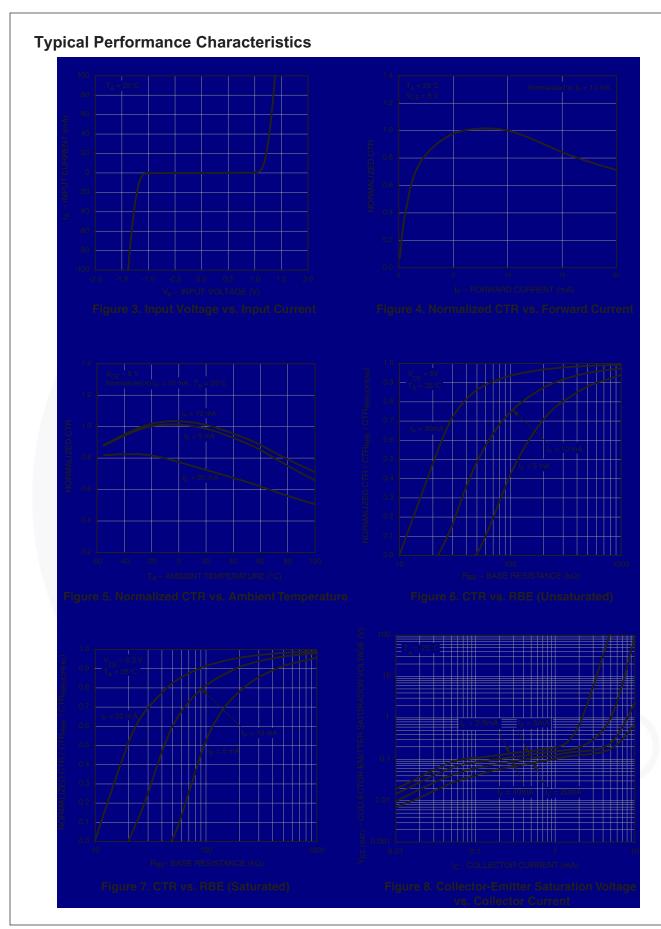
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
EMITTER						
V <sub>F</sub>	Input Forward Voltage	I <sub>F</sub> = ±10 mA		1.17	1.50	V
CJ	Capacitance	V <sub>F</sub> = 0 V, f = 1.0 MHz		80		pF
DETECTO	R					
BV <sub>CEO</sub>	Breakdown Voltage, Collector-to-Emitter	I <sub>C</sub> = 1.0 mA, I <sub>F</sub> = 0	30	100		V
BV <sub>CBO</sub>	Breakdown Voltage, Collector-to-Base	$I_C = 100 \mu A, I_F = 0$	70	120		V
BV <sub>EBO</sub>	Breakdown Voltage, Emitter-to-Base	I <sub>E</sub> = 100 μA, I <sub>F</sub> = 0	5	10		V
BV <sub>ECO</sub>	Breakdown Voltage, Emitter-to-Collector	I <sub>E</sub> = 100 μA, I <sub>F</sub> = 0	7	10		V
I <sub>CEO</sub>	Leakage Current, Collector-to-Emitter	V <sub>CE</sub> = 10 V, I <sub>F</sub> = 0		1	50	nA
C <sub>CE</sub>	Capacitance Collector to Emitter	V <sub>CE</sub> = 0, f = 1 MHz		10		pF
C <sub>CB</sub>	Collector to Base	V <sub>CB</sub> = 0, f = 1 MHz		80		pF
C <sub>EB</sub>	Emitter to Base	V <sub>EB</sub> = 0, f = 1 MHz		15		pF

#### **Transfer Characteristics**

Symbol	Characteristics	Test Conditions	Device	Min.	Тур.	Max.	Unit
CTR <sub>CE</sub>	Current Transfer Ratio,	$I_F = \pm 10 \text{ mA}, V_{CE} = 10 \text{ V}$	H11AA1M	20			%
OTTICE	Collector-to-Emitter	1F - ±10 111/1, VCE - 10 V	H11AA4M	100			%
	Current Transfer Ratio, Symmetry	$I_F = \pm 10 \text{ mA}, V_{CE} = 10 \text{ V}$ (Figure 13)	All	0.33		3.00	
V <sub>CE(SAT)</sub>	Saturation Voltage, Collector-to-Emitter	$I_F = \pm 10 \text{ mA}, I_{CE} = 0.5 \text{ mA}$	All			0.40	V

#### **Isolation Characteristics**

Symbol	Characteristic	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>ISO</sub>	Input-Output Isolation Voltage	t = 1 Minute	4170	/		VAC <sub>RMS</sub>
C <sub>ISO</sub> Isolation Capacitance		V <sub>I-O</sub> = 0 V, f = 1 MHz		0.7		pF
R <sub>ISO</sub>	Isolation Resistance	$V_{I-O} = \pm 500 \text{ VDC}, T_A = 25^{\circ}\text{C}$	10 <sup>11</sup>			Ω



## **Typical Performance Characteristics** (Continued)

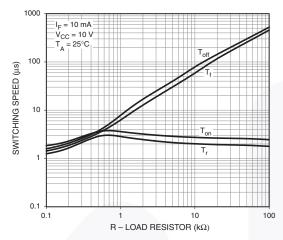


Figure 9. Switching Speed vs. Load Resistor

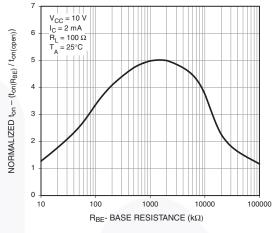


Figure 10. Normalized ton vs. RBE

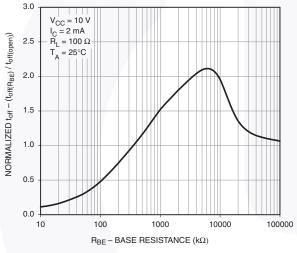


Figure 11. Normalized toff vs. RBE

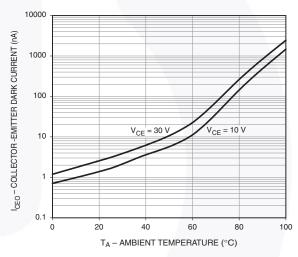


Figure 12. Dark Current vs. Ambient Temperature

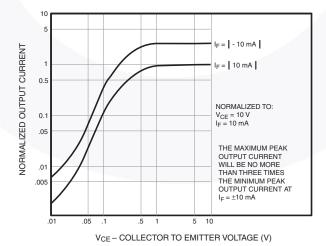


Figure 13. Output Symmetry Characteristics

#### **Reflow Profile**

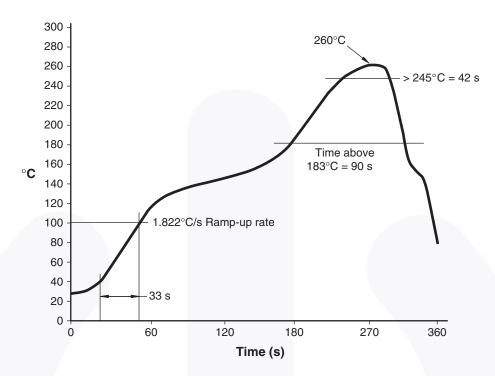


Figure 14. Reflow Profile

## **Ordering Information**

Part Number	Package	Packing Method
H11AA1M	DIP 6-Pin	Tube (50 Units)
H11AA1SM	SMT 6-Pin (Lead Bend)	Tube (50 Units)
H11AA1SR2M	SMT 6-Pin (Lead Bend)	Tape and Reel (1000 Units)
H11AA1VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	Tube (50 Units)
H11AA1SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tube (50 Units)
H11AA1SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tape and Reel (1000 Units)
H11AA1TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	Tube (50 Units)

#### Note:

2. The product orderable part number system listed in this table also applies to the H11AA4M device.

## **Marking Information**

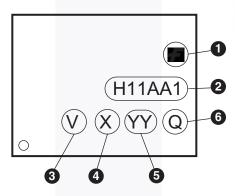
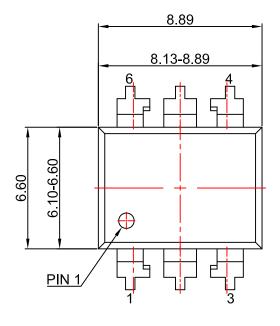
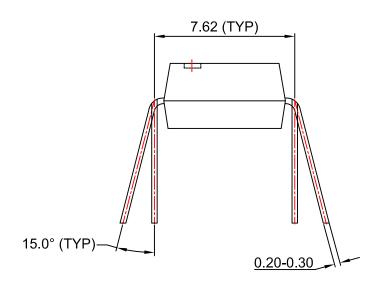


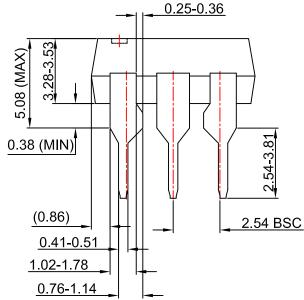
Figure 15. Top Mark

#### **Table 1. Top Mark Definitions**

_	
1	Fairchild Logo
2	Device Number
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
4	One-Digit Year Code, e.g., "5"
5	Digit Work Week, Ranging from "01" to "53"
6	Assembly Package Code



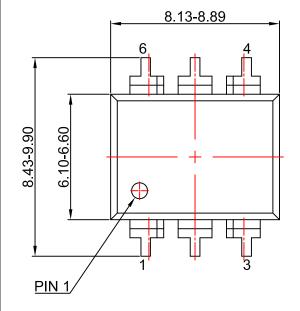


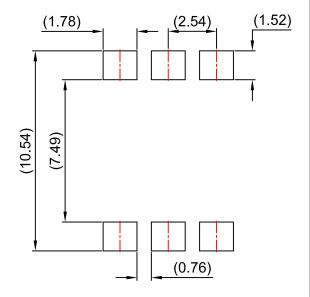


#### NOTES:

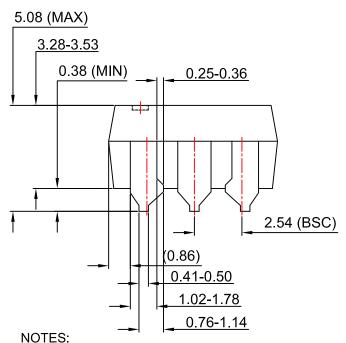
- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVSION: MKT-N06BREV4.

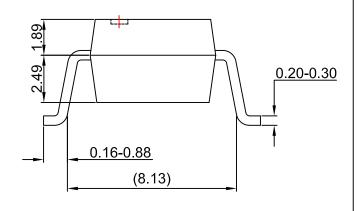






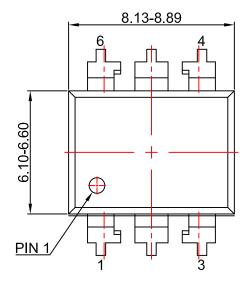
LAND PATTERN RECOMMENDATION

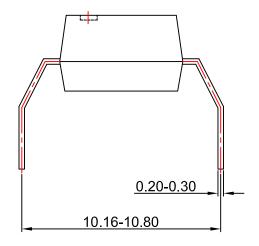


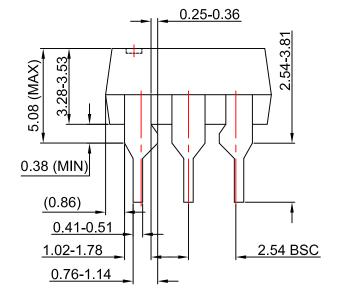


- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVSION: MKT-N06CREV4.









#### NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVSION: MKT-N06Drev4



ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and h

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative